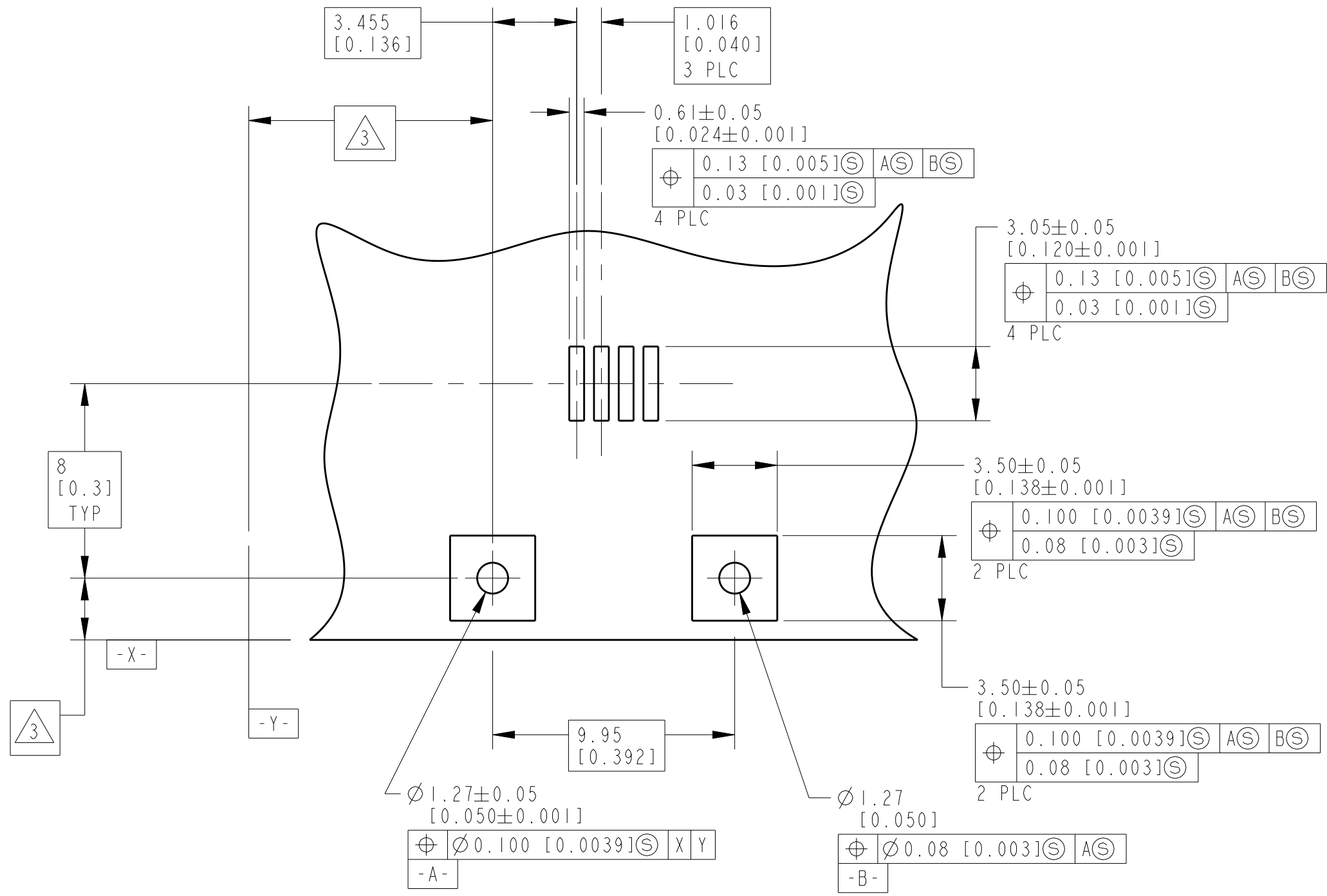
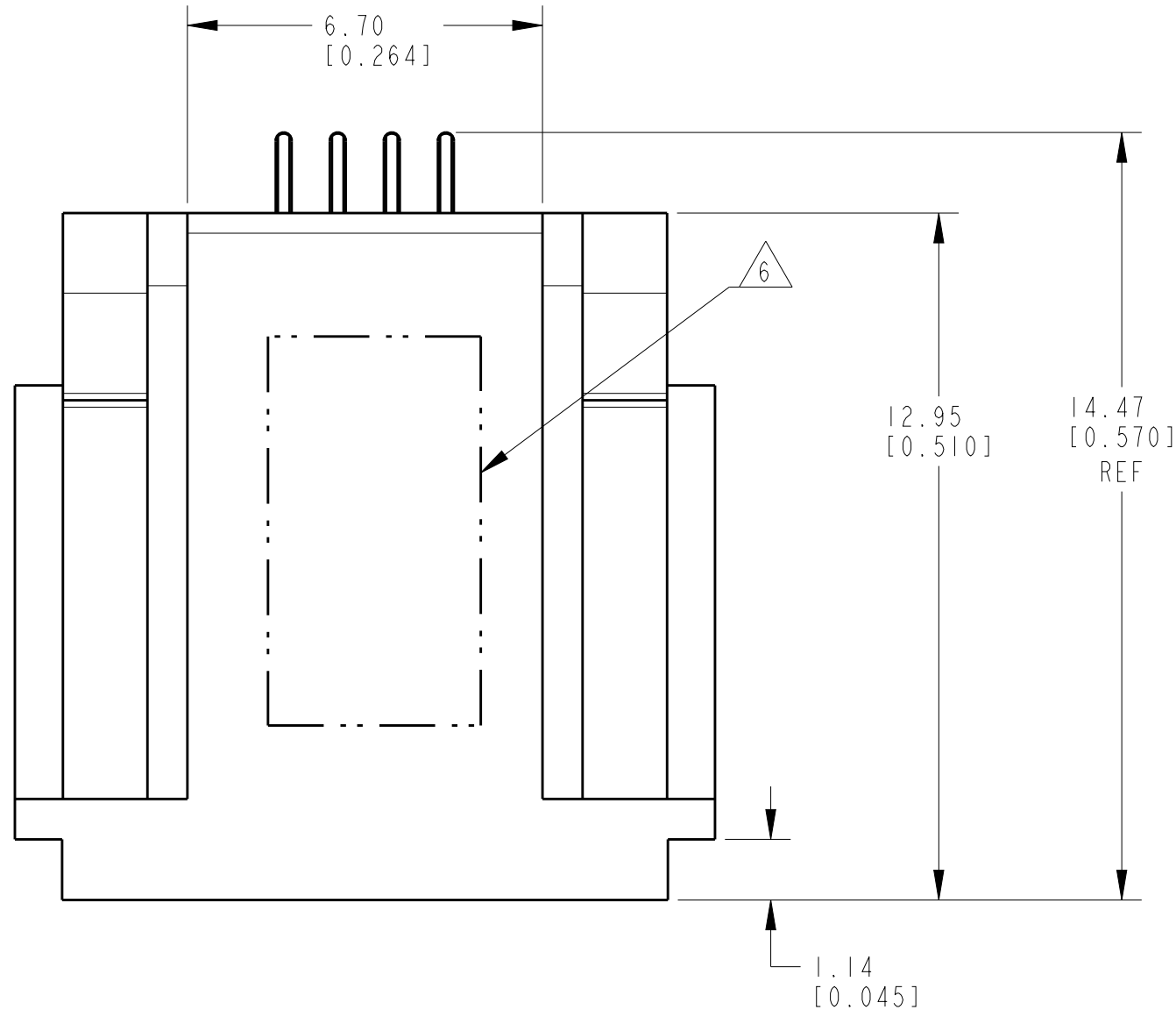
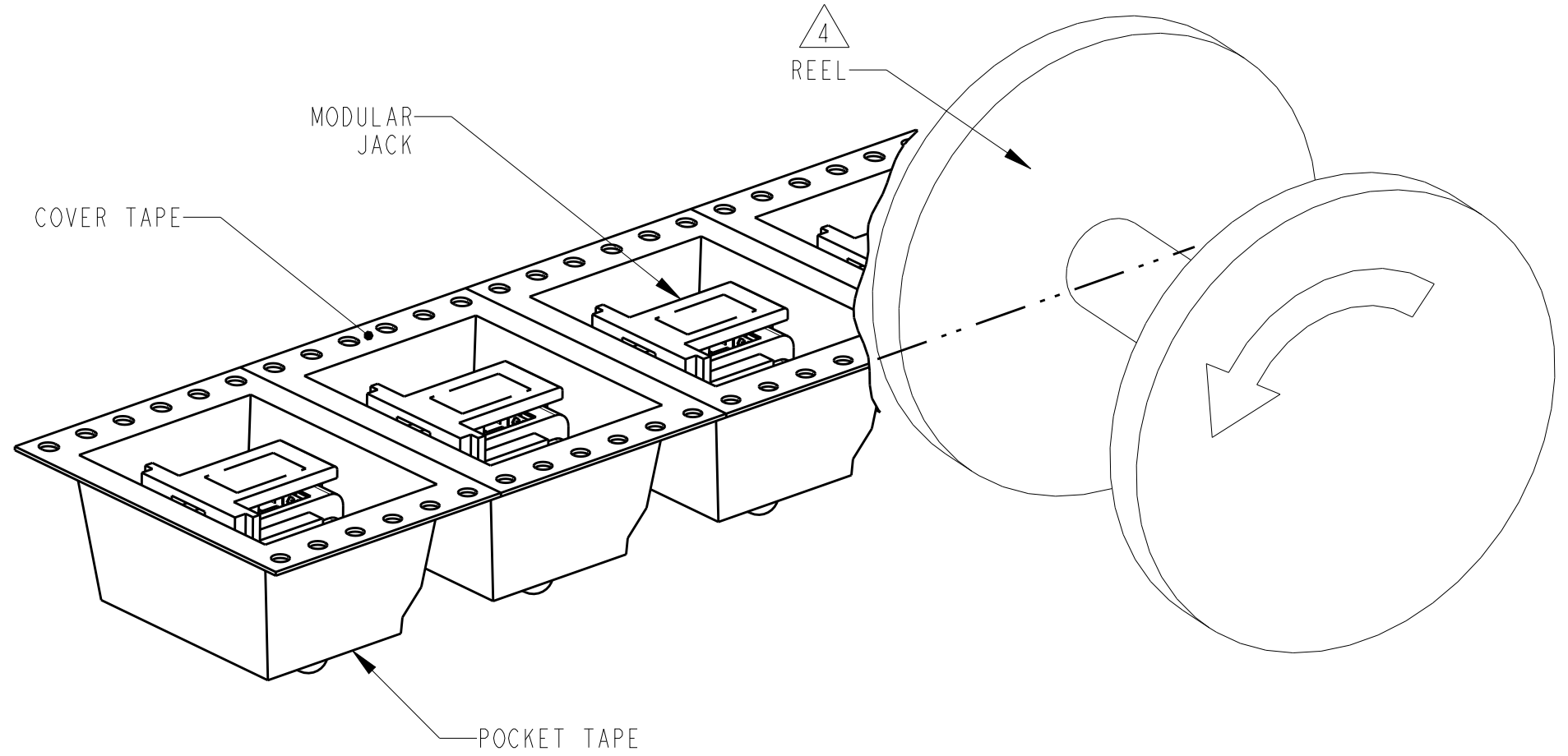
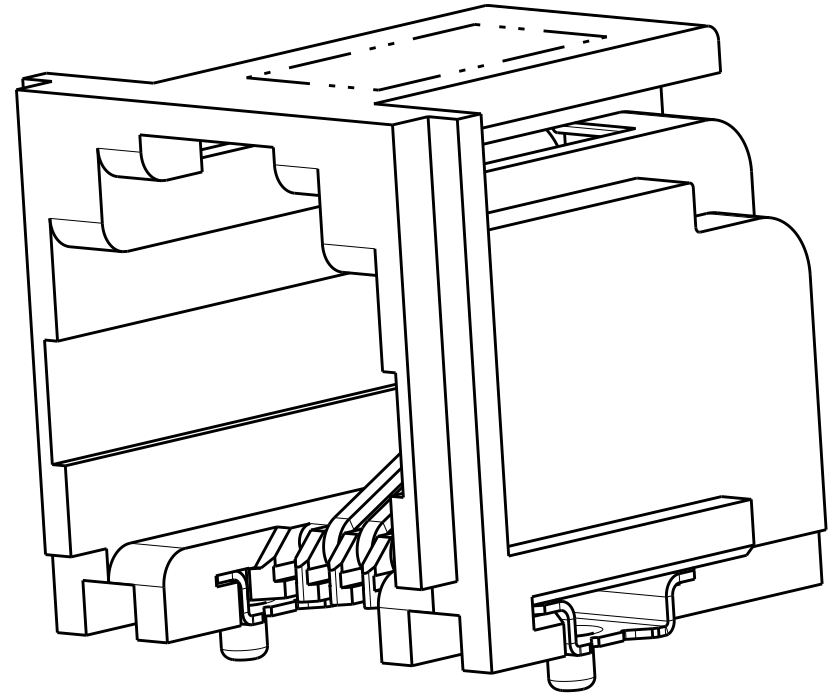
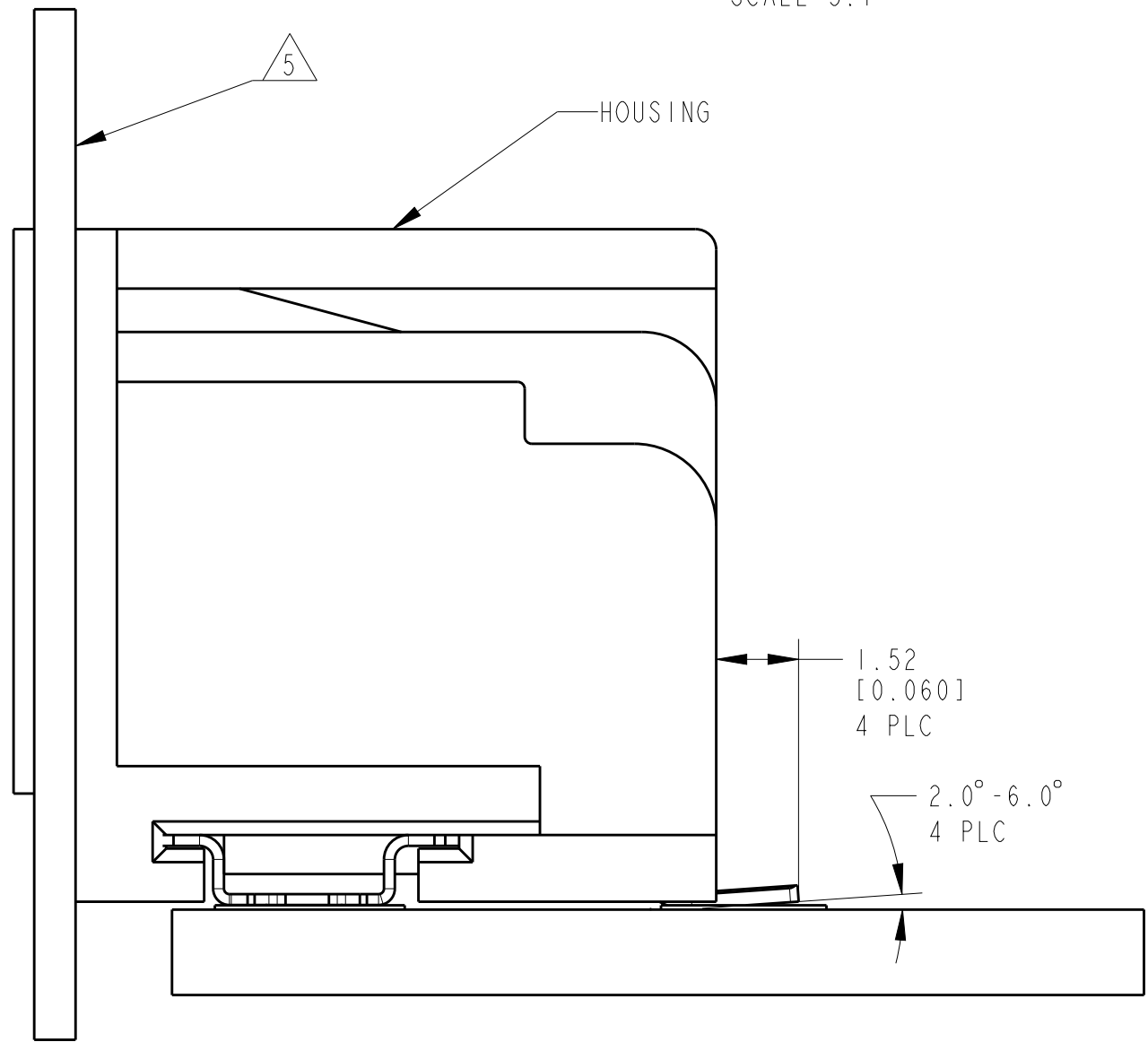


REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C	REVISED PER PER ECO-14-018192	21FEB2020	IT	SH

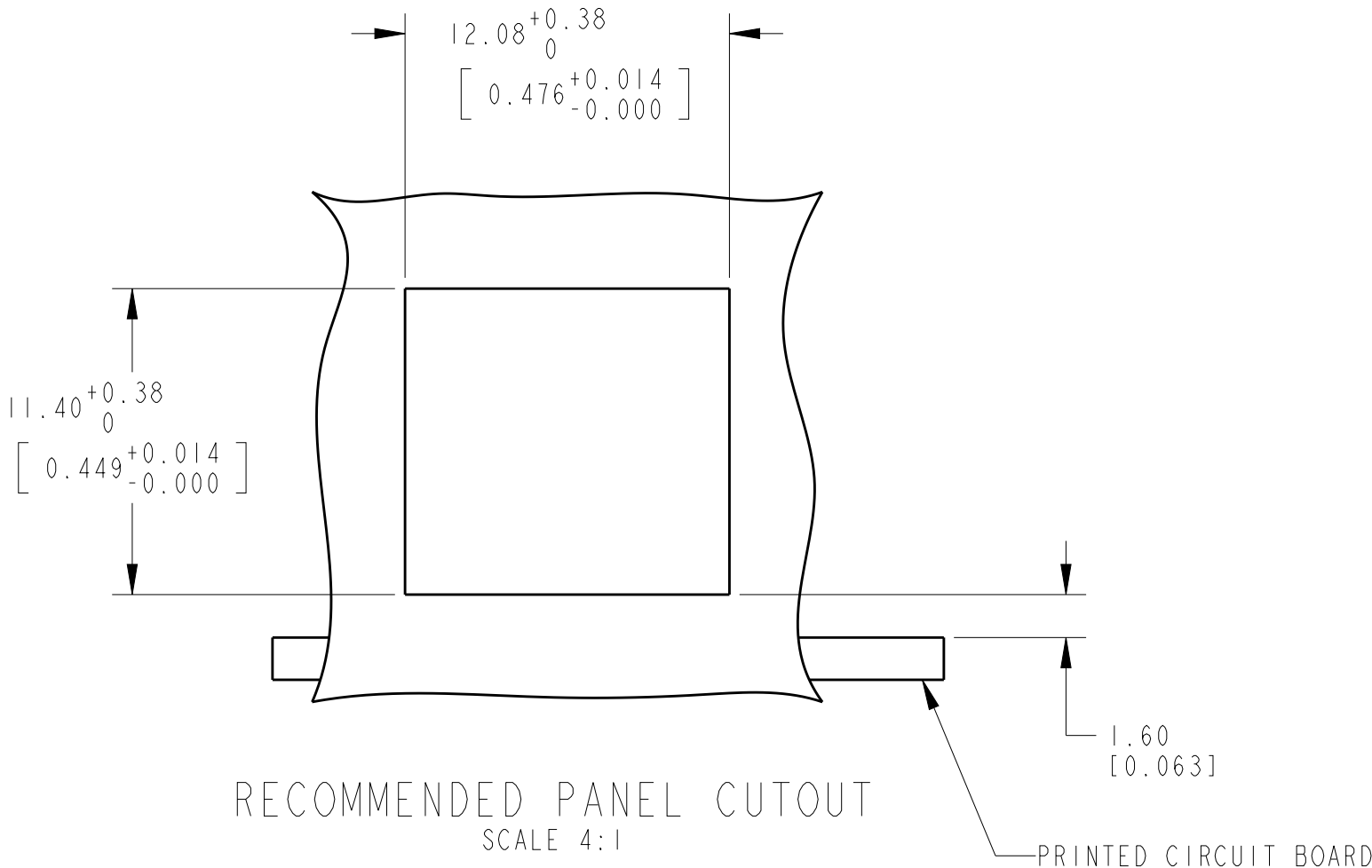


- 1 MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, PA-9T COLOR - BLACK.
TERMINALS - 0.3 [0.012] THICK COPPER ALLOY PLATED WITH
1.27µm [0.00050] MINIMUM GOLD IN LOCALIZED GOLD PLATE AREA.
2.5µm [0.000100] MINIMUM MATTE TIN ON TERMINATION END, BOTH OVER
1.27µm [0.00050] MINIMUM NICKEL OVER ENTIRE TERMINAL.
BOARDLOCK - PHOS BRONZE, 1/2 HARD, 3.81µm [0.00150] MINIMUM MATTE TIN OVER 1.27µm [0.00050] MINIMUM NICKEL ON TERMINAL END.
- 2 JACK CAVITY CONFORMS TO FCC 47 RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 DATUM ESTABLISHED BY CUSTOMER.
- 4 PACKAGING TAPE AND REEL: (PER EIA 481 SPEC)
32mm WIDE TAPE
24mm POCKET PITCH
560mm REEL DIA
600 PIECES PER REEL
- 5 CONNECTOR SHOULD BE POSITIONED THROUGH PANEL CUTOUT AS SHOWN TO SUPPORT TOP OF MODULAR JACK FOR STRAIN RELIEF
- 6 MANUFACTURING DATE CODE LOCATED APPROXIMATELY AS SHOWN.
FIRST 2 DIGITS ARE YEAR, SECOND 2 DIGITS ARE WORK WEEK, AND LAST DIGIT IS THE DAY OF THE WEEK
- 7 PACKAGING TAPE AND REEL: 32mm WIDE TAPE
24mm POCKET PITCH
330mm REEL DIA
200 PIECES/REEL
REFER 107-64184

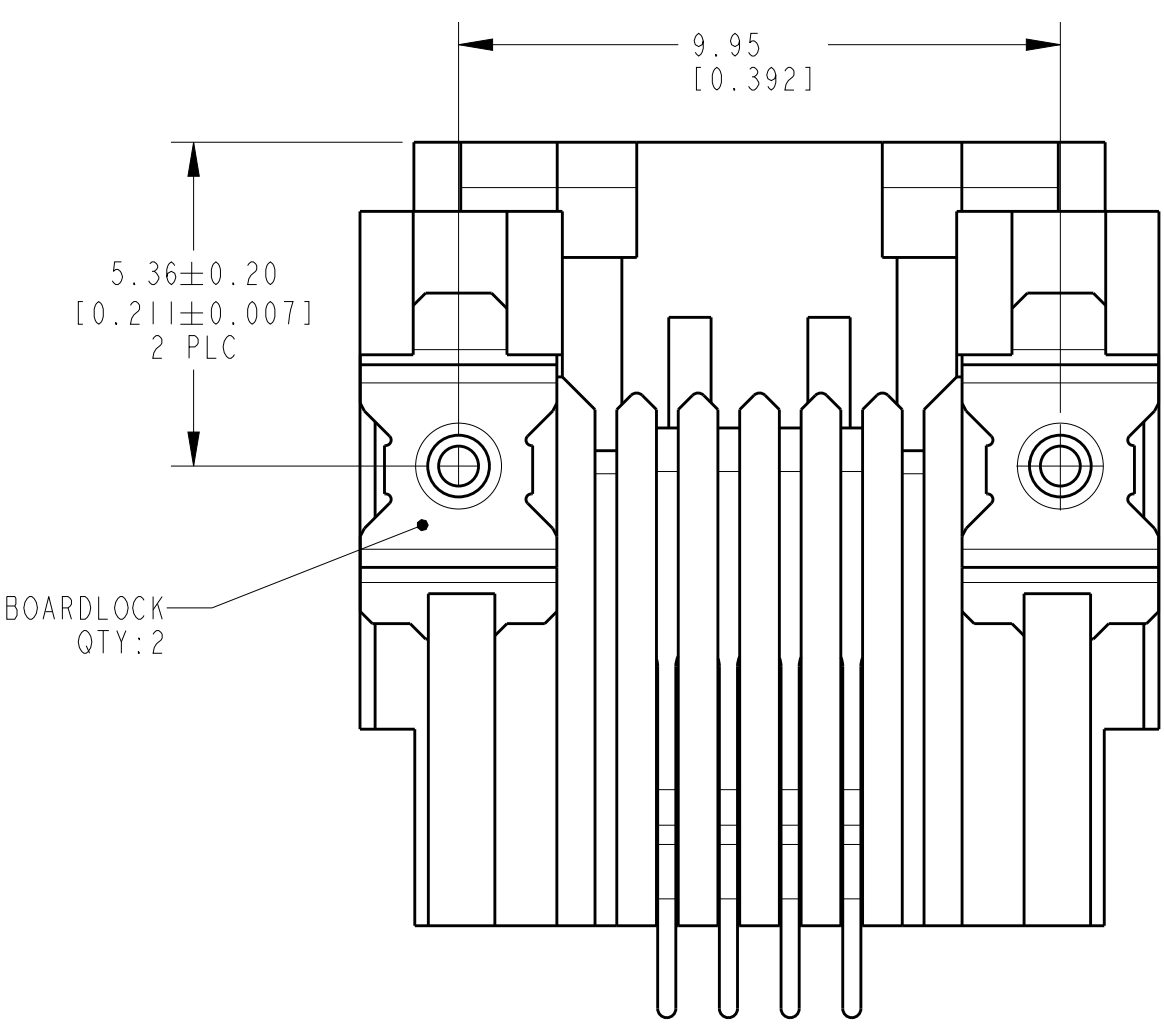
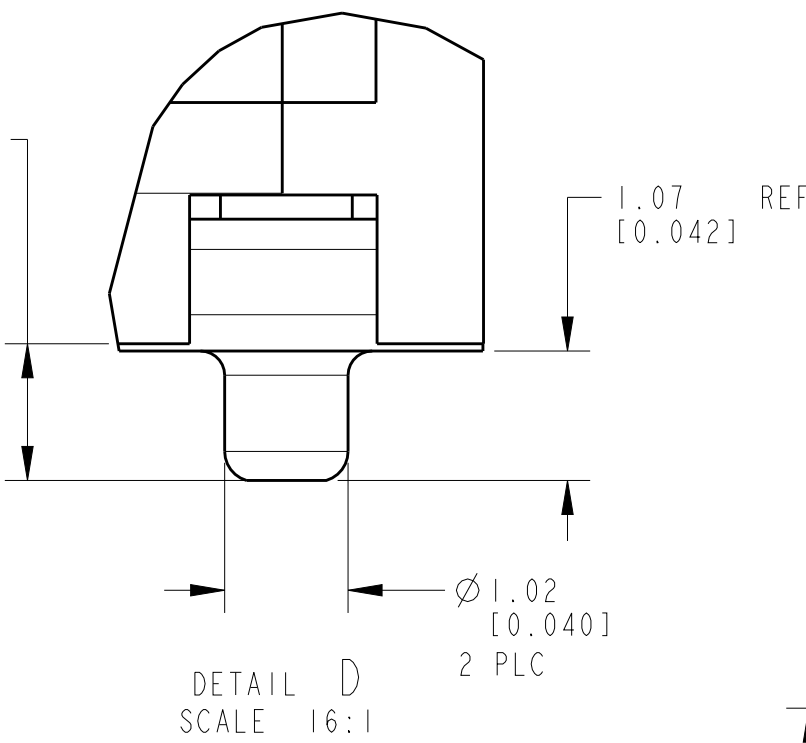
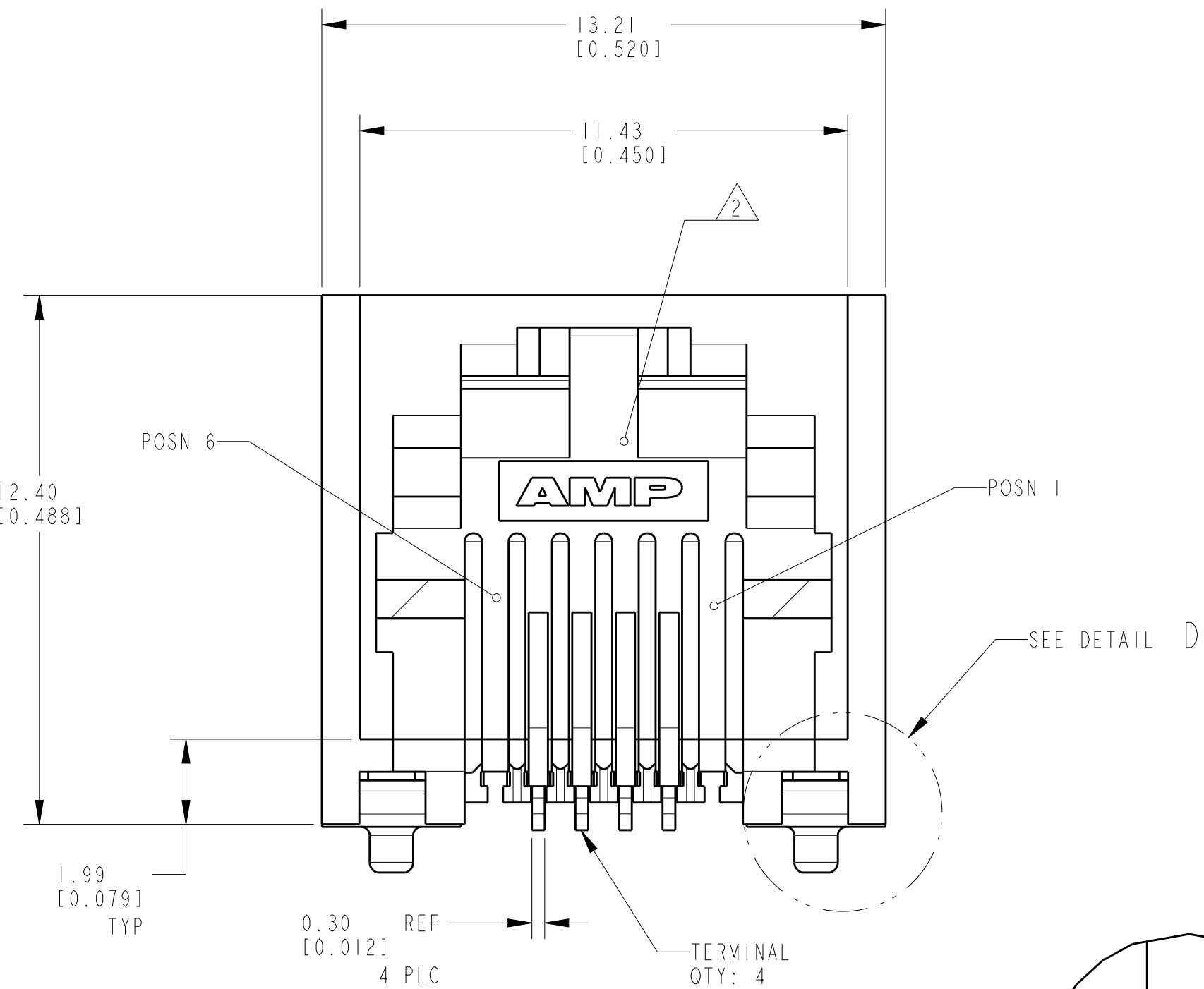
RECOMMENDED PRINTED
CIRCUIT BOARD LAYOUT
COMPONENT SIDE
SCALE 5:1



1551040-1 AS SHOWN



RECOMMENDED PANEL CUTOUT
SCALE 4:1



1551040-2	
1551040-1	
PACKAGING	PN
OBSELETE	
TE Connectivity	
MODULAR JACK ASSEMBLY, 1 PORT, 6/4 POSN, SURFACE MOUNT, RIGHT ANGLE, WITH INWARD BOARDLOCKS	
SIZE	RESTRICTED TO
00779	1551040
SCALE 8:1	SHEET 1 OF 1
REV C	

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	PREMJITH	24DEC08
DIMENSIONS:		CHK	D.CAMPSCROER	24DEC08
mm [INCHES]		APVD	T. A. ROER	24DEC08
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC		
0 PLC		108-1689		
1 PLC		APPLICATION SPEC		
2 PLC		114-6040		
3 PLC		WEIGHT		
4 PLC		RESTRICTED CUSTOMER		
ANGLES				
FINISH				
MATERIAL				
SEE NOTE 1				
SEE NOTE 1				